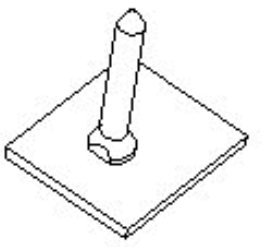
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PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 0740760005
Status: Active
Overview: vhdm__hsd
Description: VHDM-HSD™ Free-Standing Guide Pin

Documents:
Drawing (PDF) RoHS Certificate of Compliance (PDF)



Series image - Reference only

General

Product Family	Backplane Connectors
Series	74076
Application	Backplane
Application Tooling Documents	Tooling Manual
Comments	Dimension C = 6/8 row
Component Type	Guide
Overview	vhdm__hsd
Product Name	VHDM®, VHDM-HSD™
Style	N/A

Physical

Circuits (Loaded)	0
Circuits (maximum)	0
Durability (mating cycles max)	200
Keying to Mating Part	None
Number of Columns	N/A
Number of Pairs	Open Pin Field
Number of Rows	0
Orientation	N/A
PCB Retention	None
PCB Thickness Recommended (in)	0.070 In, 0.157 In
PCB Thickness Recommended (mm)	1.80 mm, 4.00 mm
Packaging Type	Bag
Pitch - Mating Interface (in)	0.000 In
Pitch - Mating Interface (mm)	0.00 mm
Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	N/A

Electrical

Current - Maximum per Contact	N/A
Data Rate	N/A
Shielded	No
Voltage - Maximum	N/A

Material Info

Reference - Drawing Numbers

Sales Drawing	SD-74076-002, SD-74076-005

VHDM, VHDM-HSD and Very High Density Metric are trademarks of Amphenol Corporation

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Not Reviewed
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

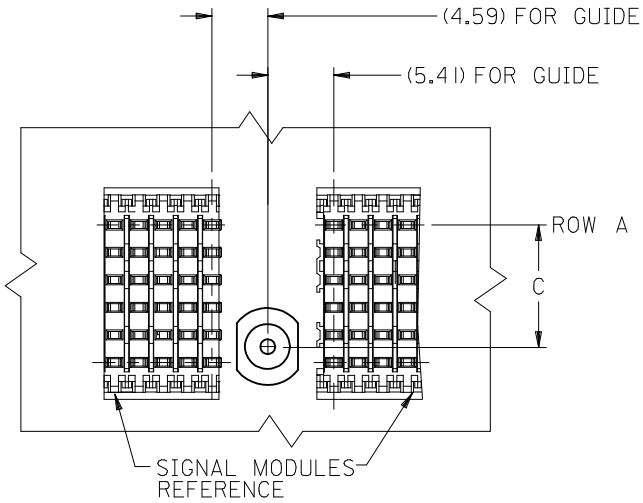
Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

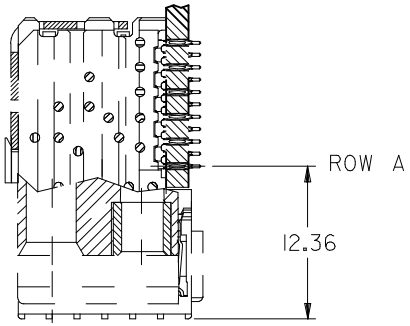
Please visit the Contact Us section for any non-product compliance questions.

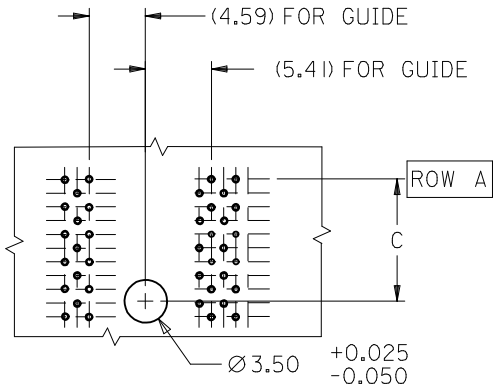
Search Parts in this Series
74076Series

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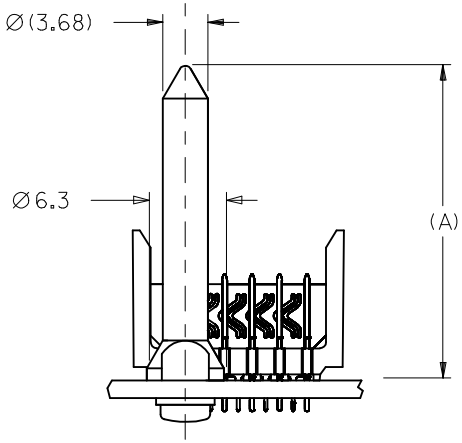
PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

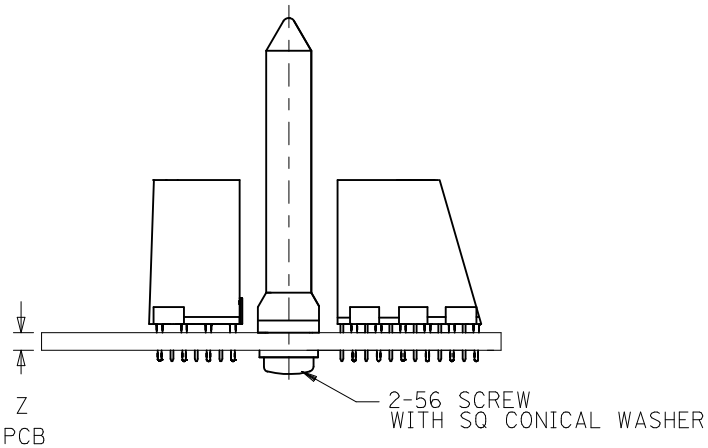






BACKPLANE HOLE PATTERN
FREE STAND GUIDE PIN





KIT NUMBER	DIM Z BOARD THICKNESS	DIM A
74076-0001	1.8-4.0	25.8
74076-0002	>4.0-9.00	25.8
74076-0005	1.8-4.0	19.9
74076-0006	>4.0-9.00	19.9

NOTES:

PACKAGING: STANDARD BULK PACK, 500 PER BAG
PACKAGE SCREWS AND GUIDE SEPARATE.

MATE WITH		DIM C
VHDM 6 ROW	GUIDE MODULE	9.96
	GROUND MODULE	9.26
	JOINER MODULE	9.26
VHDM 8 ROW	GUIDE MODULE	11.75
	GROUND MODULE	11.75
	JOINER MODULE	11.75

ADD PARTS
EC NO: UCP2009-0672
DRWN: JBINGHAM 2008/09/18
CH'KD: 2008/09/19
APPR: JLAURX 2008/09/19
DESCRIPTION
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.10	± ---
1 PLACE	± 0.15	± ---
ANGULAR ± 3 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

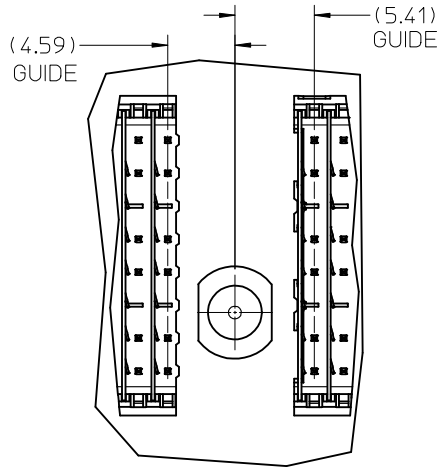
DRAWN BY: MWANG DATE: 2000/03/17
CHECKED BY: JLAURX DATE: 2000/03/20
APPROVED BY: CBIXLER DATE: 2000/03/20

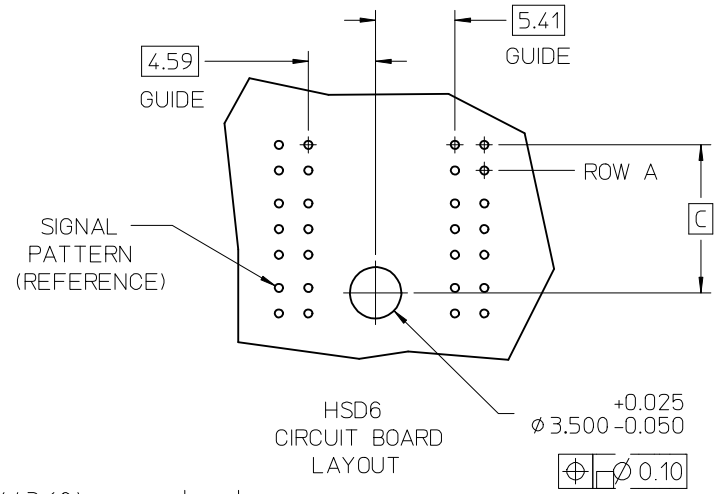
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MOLEX INCORPORATED

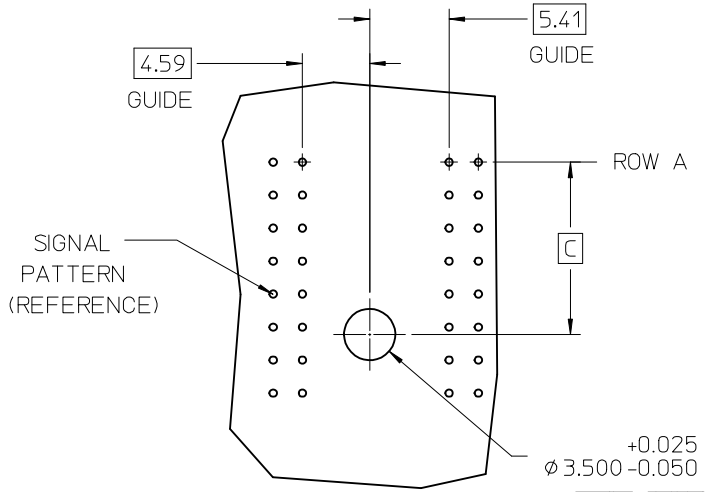
MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-74076-002
SHEET NO.: 1 OF 1
SIZE: B

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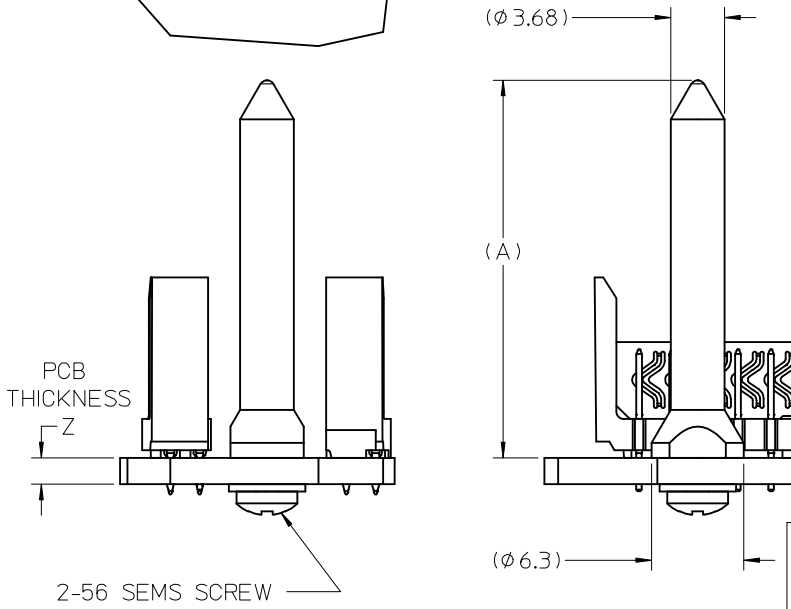




HSD6
CIRCUIT BOARD
LAYOUT



HSD8
CIRCUIT BOARD
LAYOUT



KIT NUMBER	DIM Z BOARD THICKNESS	DIM A
74076-0001	1.8 - 4.0	25.8
74076-0002	>4.0 - 9.0	25.8
74076-0005	1.8 - 4.0	19.9
74076-0006	>4.0 - 9.0	19.9

MATE WITH		DIM C
HSD 6	GUIDE MODULE	10.09
	GROUND MODULE	9.39
	JOINER MODUEL	9.39
HSD 8	GUIDE MODULE	11.75
	GROUND MODULE	11.75
	JOINER MODULE	11.75

NOTES:
1. PARTS TO BE BULK PACKED, 500 PER BAG.
2. SCREWS & GUIDE PINS PACKAGED SEPARATELY.

ADD PARTS
EC NO: UCP2009-0672 2008/09/18
DRWN: JBINGHAM 2008/09/19
CH'KD:
APPR: JLAURX 2008/09/19
DESCRIPTION
B
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.10	± ---
1 PLACE	± 0.15	± ---
ANGULAR ±---°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 3:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	JBINGHAM	2007/03/28
CHECKED BY	SREED	2007/03/28
APPROVED BY	SREED	2007/03/28

TITLE: HSD BACKPLANE FREE STANDING GUIDE PIN SALES DRAWING

MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-74076-005
SHEET NO.: 1 OF 1
SIZE: B

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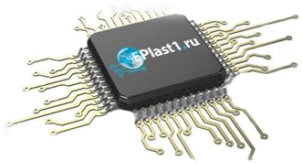
Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

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- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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Факс: 8 (812) 320-02-42
Электронная почта: org@eplast1.ru
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